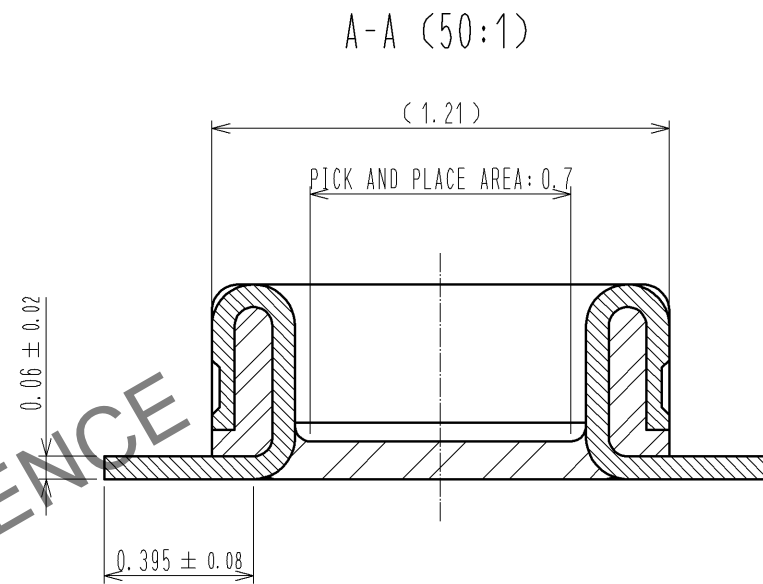
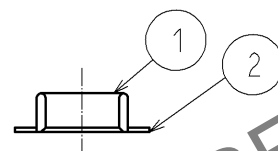
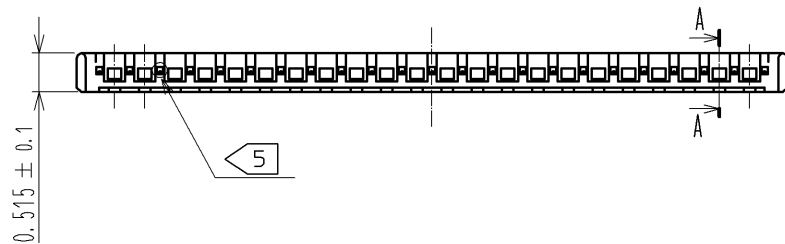
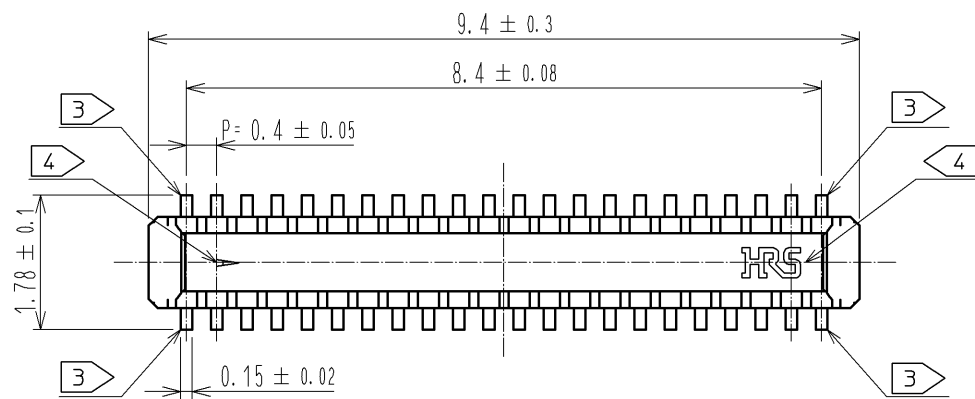
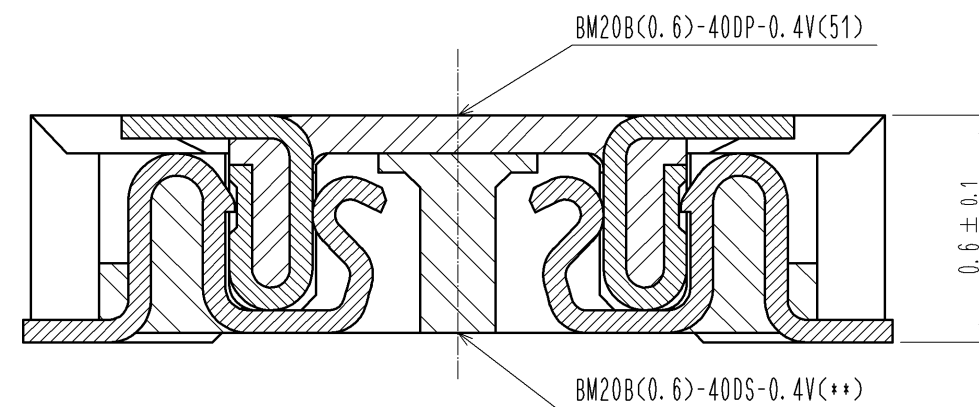


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ENGAGEMENT FIGURE (50:1)



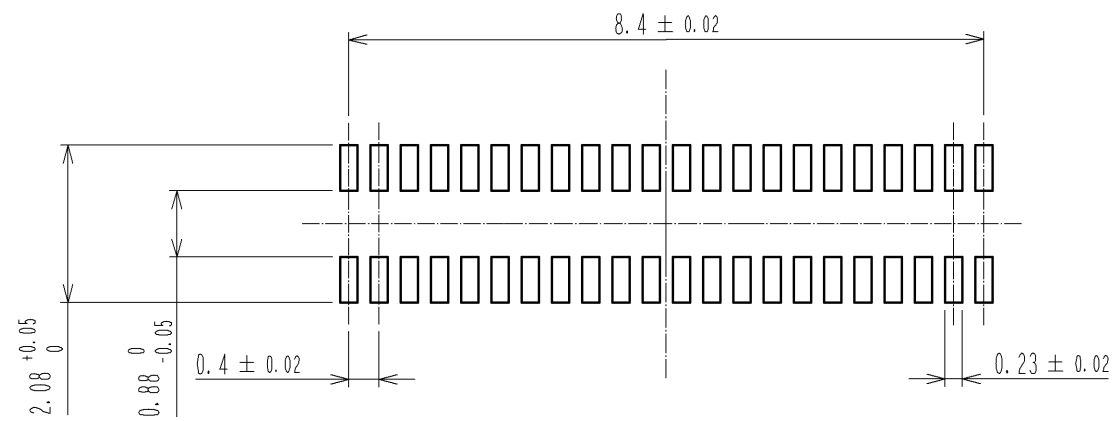
- NOTE 1 . ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
2 . CONTACT PLATING SPECIFICATIONS
CONTACT AREA : GOLD 0.05 μ m MIN
SMT LEAD : GOLD 0.05 μ m MIN
UNDER PLATING : NICKEL 1 μ m MIN
(SURFACE : SEALING)
3 . EACH CONTACTS AT 4 CORNERS ARE PROVIDED FOR METAL FITTINGS.
4 . HRS MARK AND CAV No. ARE INDICATED IN APPROX POSITION SHOWN.
5 . A PART OF THE WALL COULD BE NOTCHED.

3	PS	CLEAR (EMBOSSED CARRIER TAPE)		6	PS	CLEAR (REINFORCEMENT COLLAR)	
2	PHOSPHOR BRONZE	2		5	PS	BLACK (PLASTIC REEL)	
1	LCP	UL94 V-0, BLACK		4	POLYESTER	CLEAR (COVER TAPE)	
NO.	MATERIAL	FINISH . REMARKS		NO.	MATERIAL	FINISH . REMARKS	

UNITS mm		SCALE 10 : 1		COUNT 1	DESCRIPTION OF REVISIONS DIS-H-008208		DESIGNED KR. AJITO	CHECKED TS. MIYAZAKI	DATE 13. 10. 09
 HIROSE ELECTRIC CO., LTD.		APPROVED : KH. IKEDA		13. 07. 11	DRAWING NO. EDC3-347092-01				
		CHECKED : WR. FUKUCHI		13. 07. 11	PART NO. BM20B(0.6)-40DP-0.4V(51)				
		DESIGNED : RT. SHIMIZU		13. 07. 10	CODE NO. CL684-9305-0-51				
		DRAWN : Hongwoo. Jo		13. 07. 09	 				

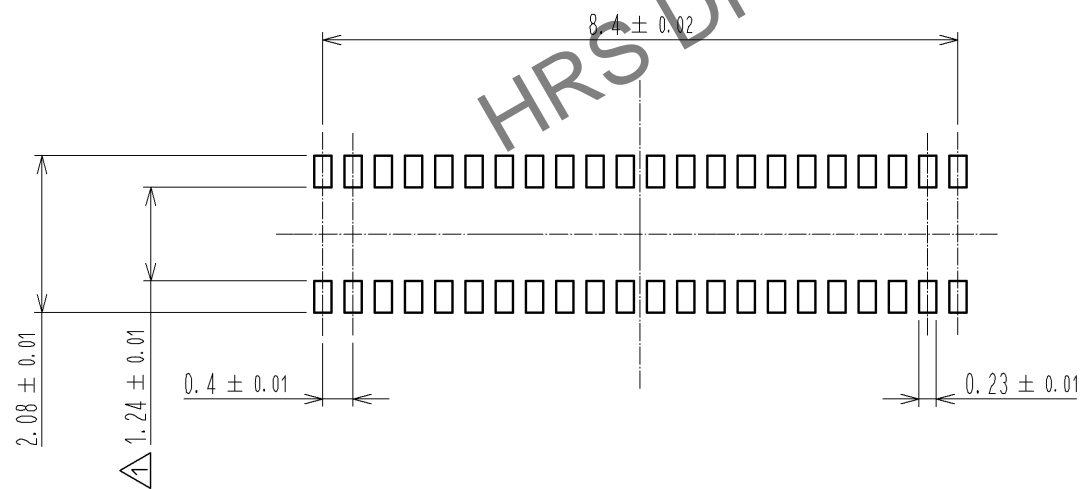
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◆RECOMMENDED PCB LAYOUT

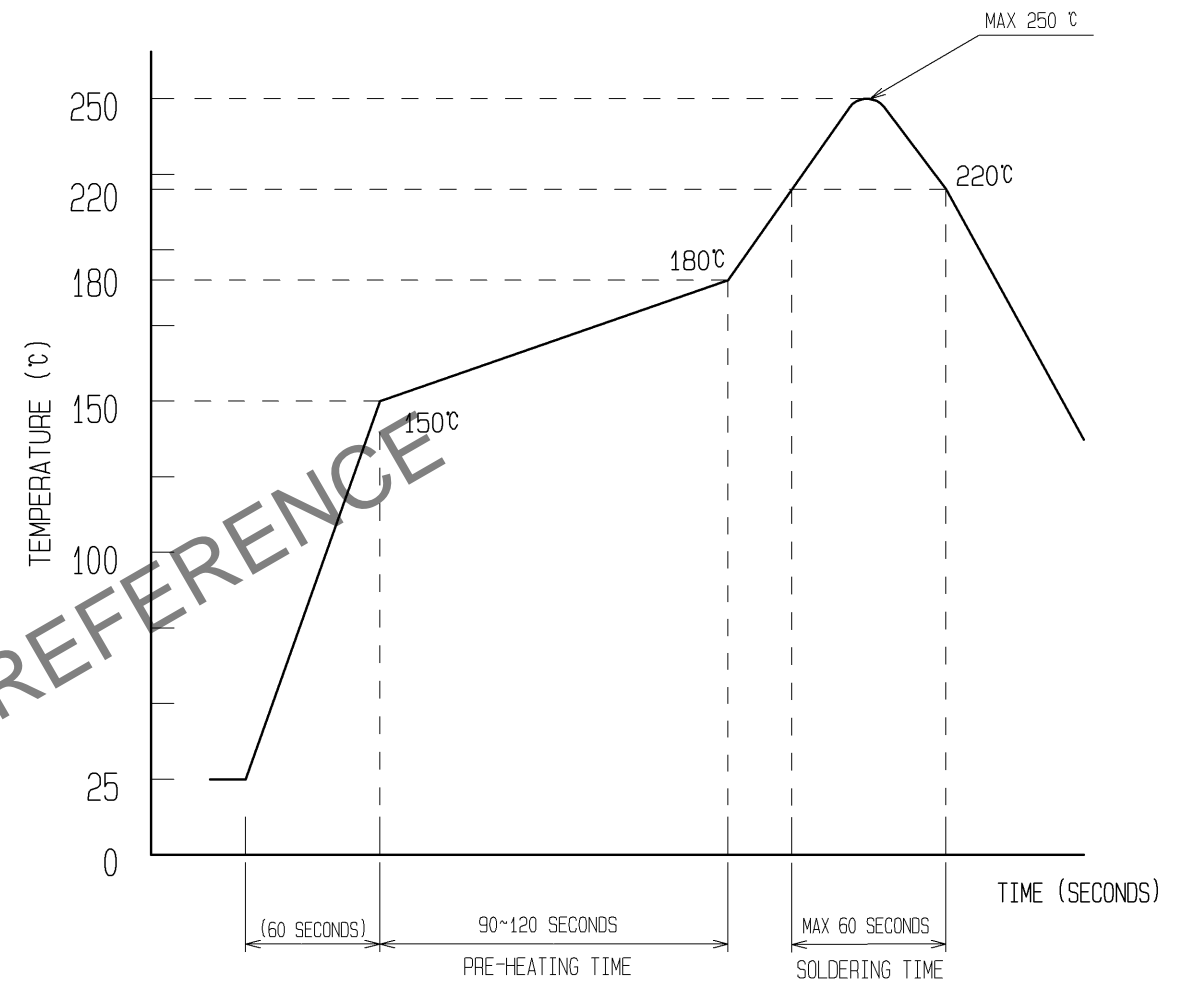


◆RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : $100 \mu\text{m}$



6> RECOMMENDED REFLOW TEMPERATURE PROFILE
USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD:IR REFLOW
NUMBER OF REFLOW CYCLES:2 CYCLES MAX.
1)REFLOW TIME
DURATION ABOVE 220 $^{\circ}\text{C}$. 60 SEC MAX.
(PEAK TEMPERATURE:250 $^{\circ}\text{C}$ MAX)
2)PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN):150 $^{\circ}\text{C}$
PRE-HEAT TEMPERATURE(MAX):180 $^{\circ}\text{C}$
PRE-HEAT TIME:90-120 SEC.

6> THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE.
ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND
OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE,
A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED
PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS

DRAWING NO.	EDC3-347092-01
PART NO.	BM20B<0.6>-40DP-0.4V<51>
CODE NO.	CL684-9305-0-51

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